

SPECIFICATION SHEET

SPECIFICATION SHEET NO.	R0412- CR0201JM3K3S01			
DATE	Apr. 12, 2024			
REVISION	A1 Updated With Most Recent Data			
DESCRIPTION AND MAIN PARAMETRICS	Thick Film Chip Resistors, 0201 (0603 Metric), CR01 Series, Dimension L0.60*W0.30*H0.23mm, 2 Terminations Tolerance: ±5%, Resistance 3.3K ohm, Dissipation Max. 1/20W @ 70°C			
	Temperature Coefficient Rate (TCR) Max. ±200ppm/°C Operating Temp. Range -55°C ~+125°C Package in Tape/Reel, 15,000pcs/Reel RoHS/RoHS III compliant and HF			
CUSTOMER				
CUSTOMER PART NO.				
CROSS REF. PART NO.				
ORIGINAL MFG/PART NO.	Aillen/CR01JM3K3			
PART CODE	CR0201JM3K3	501		

VENDOR APPROVE Issued/Checked/Approved omp mpo mpo Ruby Zhang Jack Zhang Mandy Xu

DATE: Apr. 12, 2024

CUSTOMER APPROVE DATE: 1 4/12/2024



PART CODE: CR0201JM3K3S01 THICK FILM CHIP RESISTORS CR01 SERIES

DESCRIPTION

The resistors are constructed in a high grade ceramic body (aluminum oxide). Internal metal electrodes are added at each end and connected by a resistive paste that is applied to the top surface of the substrate. The composition of the paste is adjusted to give the approximate resistance required and the value is trimmed to within tolerance by laser cutting of this resistive layer. The resistive layer is covered with a protective coat. Finally, the two external end terminations are added. For ease of soldering the outer layer of these end terminations is a Tin (lead free) alloy.

MAIN FEATURE

- High Reliability And Stability
- Reduced Size Of Final Equipment
- Lower Assembly Costs
- Higher Component And Equipment Reliability
- RoHS III Compliant And Halogen Free Products

APPLICATION

- Consumer Electrical Equipment
- EDP, Computer Application
- Telecom Application

HOW TO ORDER

Please indicate pat code OR custom parameters code and send us your RFQ by E-mail



4/12/2024

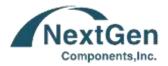


THICK FILM CHIP RESISTORS CR01 SERIES

PART CODE GUIDE



CODE	NAME	KEY SPECIFICATION OPTION
CR	Product code	Thick Film Chip Resistors
0201	Size Code	0201 (0603): L0.60*W0.30mm
J	Resistance Range Tolerance Code	P: Jumper; B: +/-0.1%; D: +/-0.5%; F: +/-1%; J: +/-5%
М	Package Code	A: 4Kpcs/7"Reel; B:5kpcs/7"Reel; C:10kpcs/7"Reel; M:15kpcs/7"Reel; D:10kpcs/10"Reel; E:20kpcs/10"Reel
3K3	Resistance value code	OR: Oohm; 1R2: 1.2ohm; 10R: 10ohm; 20R: 20ohm; 51R: 51ohm; 240R: 240ohm; 390R: 390ohm; 1K:1Kohm; 10K: 10Kohm; 3K3: 3.3Kohm; 6K2: 6.2Kohm; 25K5: 25.5Kohm; 100K: 100Kohm; 820K: 820Kohm; 1M: 1.0Mohm; 1M2: 1.2Mohm
S01	Internal control code	Custom letter A~Z, a-z or digits (0-9)



THICK FILM CHIP RESISTORS CR01 SERIES

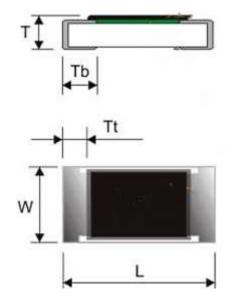
DIMENSION (Unit: mm)

Image for reference

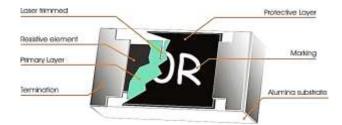


General Marking: Blank

CR01 series



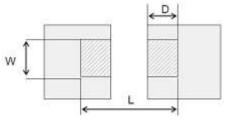
Item	Dimension			
L	0.60±0.03			
w	0.30±0.03			
т	0.23±0.03			
Тb	0.15±0.05			
Tt	0.10±0.05			



Recommended Solder Pad

Resistors Construction

For Reference



ltem	Dimension (mm)			
w	0.25~0.30			
L	0.70~0.90			
D	0.30~0.40			

4/12/2024

NextGen Components, Inc.

4



THICK FILM CHIP RESISTORS CR01 SERIES

GENERAL ELECTRONICAL CHARACTERISTICS

	ltem		Symbol	Characteristic	Condition		
Pro	Product Name		CR	Thick Film Chip Resistors			
	Size		Size		0201	CR01 Series, L0.60*W0.30*H0.23mm	
Resist	tance Range	Ω		3.3K			
Resista	Resistance Tolerance		J	+/-5			
TCR	TCR 10Ω~10ΜΩ			≤±200			
	1Ω~9.76Ω			-200~+600			
Max.	Dissipation	w		1/20	@ Tamb=70°C		
Operatir	ng Temperature	°C		-55 ~+125			
Max. Ope	Max. Operation Voltage			25	@DC or RMS		
Max. Ov	erload Voltage	V		50	@DC or RMS		

Note

1) This is the maximum voltage that may be continuously supplied to the resistor element, see "IEC publication 60115-8"

2) Max. Operation Voltage : So called RCWV (Rated Continuous Working Voltage) is determined by

RCWV = $\sqrt{Rated Power \times Resistance Value}$ or Max. RCWV listed above, whichever is lower.

3) Test condition for jumper (0 Ω)

ITEM	UNIT	SYMBOL	CHARACTERISTIC	CONDITION
Power Rating At 70°C	W		1/20	
Max. Resistance	mΩ		50	
Rated Current	А		1.0	
Peak Current	A		2.5	
Operating Temperature	°C		-55 ~+125	

4/12/2024



THICK FILM CHIP RESISTORS CR01 SERIES

PRODUCT CHARACTERIZATION

Standard values of nominal resistance are taken from the E24 & E96 series for resistors with a tolerance Of +/-0.1%, +/-0.5%, +/-1% & +/-5%, The values of the E24/E96 series are in accordance with "IEC publication 60063"

DERATING

The power that the resistor can dissipate depends on the operating temperature; see Fig.1

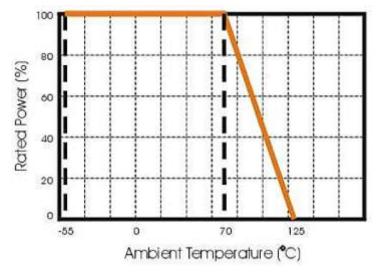


Fig 1 Maximum dissipation in percentage of rated power as a function of the ambient temperature for CR01

MOUNTING

Due to their rectangular shapes and small tolerances, Surface Mountable Resistors are suitable for handling by automatic placement systems. Chip placement can be on ceramic substrates and printed-circuit boards (PCBs). Electrical connection to the circuit is by individual soldering condition. The end terminations guarantee a reliable contact.

STORAGE AND HANDLING CONDITIONS

1) Products are recommended to be used up within two years since operation date as ensured shelf life. Check solderability in case shelf life extension is needed.

2) To store products with following condition: Temperature : 5 to 40°C Humidity: 20 to 70% relative humidity

3) Don't store products in a corrosive environment such as sulfide, chloride gas, or acid. It may cause oxidization of electrode, which easily be resulted in poor soldering b.To store products on the shelf and avoid exposure to moisture. Don't expose products to excessive shock, vibration, direct sunlight and so on.

4/12/2024



PART CODE: CR0201JM3K3S01 THICK FILM CHIP RESISTORS CR01 SERIES

REFLOW SOLDERING CONDITION

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260 °C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs). Surface Mount Resistors are tested for solderability at 235 °C during 2 seconds. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2.

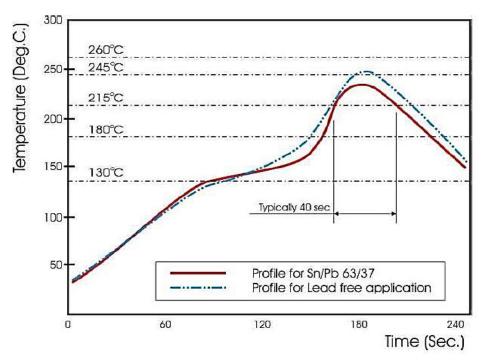


Fig 2. Infrared soldering profile for Chip Resistors

TEST AND REQUIREMENTS

Essentially all tests are carried out according to the schedule of IEC publication 115-8, category LCT/UCT/56(rated temperature range: Lower Category Temperature, Upper Category Temperature; damp heat, long term, 56 days). The testing also meets the requirements specified by EIA, EIAJ and JIS. The tests are carried out in accordance with IEC publication 68, "Recommended basic climatic and mechanical robustness testing procedure for electronic components" and under standard atmospheric conditions according to IEC 60068-1, subclause 5.3. Unless otherwise specified, the following value supplied Temperature: 15 °C to 35 °C. Relative humidity: 45% to 75%. Air pressure: 86kPa to 106 kPa (860 mbar to 1060 mbar). All soldering tests are performed with midly activated flux.

4/12/2024



THICK FILM CHIP RESISTORS CR01 SERIES

TEST AND REQUIREMENT (JIS C 5201-1: 1998)

TEST	PROCEDURE / TEST METHOD	REQUIREMENT		
		Resistor	0Ω	
Electrical	- DC resistance values measurement	Within the	<50mΩ	
Characteristics	- Temperature Coefficient of Resistance (T.C.R)	specified tolerance		
JISC5201-1: 1998	Natural resistance change per change in degree	Refer to "QUICK		
Clause 4.8	centigrade. $\frac{R_2 - R_1}{R_1(t_2 - t_1)} \times 10^6 \text{ (ppm/°C)}$	REFERENCE DATA"		
	t1 : 20°C+5°C-1°C; t2 : -55°C or +125°C			
	R1 : Resistance at reference temperature			
	(20°C+5°C/- 1°C)			
	R2: Resistance at test temperature (-55°C or +125°C)			
Short time overload	Permanent resistance change after a 5second	ΔR/R max.	<50mΩ	
(S.T.O.L) Clause 4.13	application of a voltage 2.5 times RCWV or the	±(2%+0.10Ω)		
	maximum overload voltage specified in the above list,			
	whichever is less.			
Resistance to	Un-mounted chips completely immersed for	ΔR/R max.	<50mΩ	
soldering heat(R.S.H)	10±1second in a SAC solder bath at 260°C±5°C	± (1%+0.05Ω)		
Clause 4.18		no visible damage		
Solderability	Un-mounted chips completely immersed for 2±0.8	95% coverage min., g	jood	
Clause 4.17	second in a SAC solder bath at $235^{\circ}C\pm 5^{\circ}C$	tinning and no visible	damage	
Temperature cycling	30 minutes at -55°C±3°C, 2~3 minutes at 20°C+5°C-	ΔR/R max.	<50mΩ	
Clause 4.19	1°C, 30 minutes at +125°C±3°C, 2~3 minutes at	±(1%+0.05Ω)		
	20°C+5°C1°C, total 5 continuous cycles			
Damp Heat	1000 +48/-0 hours, loaded with RCWV or Vmax in	10Ω≤R<1MΩ :	<50mΩ	
(Load life in humidity)	humidity chamber controller at 40°C±2°C and	ΔR/R max.		
Clause 4.24	90~95% relative humidity, 1.5hours on and 0.5 hours	±(3%+0.10Ω)		
	off	R<10Ω, R≥1MΩ :		
		ΔR/R max.		
		±(5%+0.10Ω)		

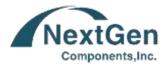
4/12/2024



THICK FILM CHIP RESISTORS CR01 SERIES

TEST AND REQUIREMENT (JIS C 5201-1: 1998)

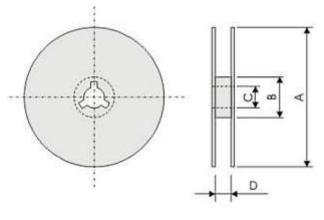
TEST	PROCEDURE / TEST METHOD	REQUIREMENT	
		Resistor	0Ω
Load Life (Endurance) Clause 4.25	1000+48/-0 hours; loaded with RCWV or V max in chamber controller 70±2ºC, 1.5 hours on and 0.5 hours off	Ditto.	
Bending strength Clause 4.33	Resistors mounted on a 90mm glass epoxy resin PCB(FR4), bending once 5mm for 10sec	No visual damaged, ΔR/R max. ±(1%+ 0.05Ω)	<50mΩ
Adhesion Clause 4.32	Pressurizing force: 3N, Test time: 10±1sec.	No remarkable dama removal of the termi	



THICK FILM CHIP RESISTORS CR01 SERIES

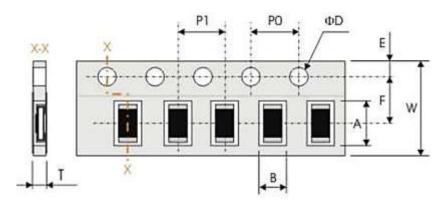
REEL DIMENSION (Unit: mm)

7": 15,000Ppcs/Reel



Code	Dimension 7"	Dimension 10"	Dimension 13"	
A	178.0+/-2.0	254.0+/-2.0	330.0+/-2.0	
В	60.0 +/-1.0	100 +/-1.0	100+/-1.0	
С	13.0+/-0.20	13.0+/-0.20	13.0+/-0.20	
Т	9.0+/-0.50	9.0+/-0.5	9.0+/-0.5	

TAPE DIMENSION (Unit: mm)



Code	Dimension		
А	0.67±0.05		
В	0.37±0.05		
W	8.00±0.20		
F	3.50±0.05		
E	1.75±0.10		
P 1	2.00±0.05		
PO	4.00±0.05		
ΦD	1.50±0.10		
Т	0.45±0.05		

TAPING QUANTITY AND TAPE MATERIAL

Таре	Paper Tape						Embossed Tape	Bulk Cassette
		4 mm Pitch	2 mm Pitch				4 mm Pitch	
Reel Size	7"	10"	13″	7"	10"	13"	7"	
CR01	-	-	-	15000pcs	-	-	-	-



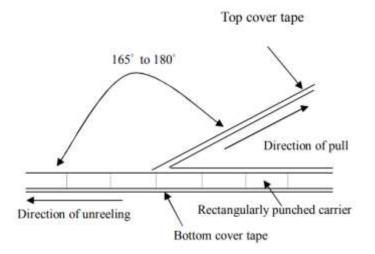
THICK FILM CHIP RESISTORS CR01 SERIES

PERFORMANCE OF TAPING

Strength of Carrier Tape and Top Cover Tape

Carrier Tape: When a tensile force 1.02kgf is applied in the direction of unreeling the tape, the tape shall withstand this force. Top cover Tape: When a tensile force 1.02kgf is applied to the tape, the tape shall withstand this force. Peel Force of Top Cover Tape

Unless otherwise specified, the peel force of top cover tape shall be 10.2 to 71.4 g f when the top cover tape is pulled at a speed of 300mm/min with the angle between the taped during peel and the direction of unreeling maintained at 165 to 180°as illustrated in Fig.





THICK FILM CHIP RESISTORS CR01 SERIES

ROHS COMPLIANCE

 The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU RoHS Directive (EU) 2015/863 EC (RoHS3). RoHS Test Report for this product can be obtained can be obtained at Download Center.

REACH COMPLIANCE

 REACH substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, REACH Test Report for this product can be obtained can be obtained at Download Center.

IMPORTANT NOTES AND DISCLAIMER

- All Product parametric performance is indicated in the Electrical Characteristics for the listed herein test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.
- 2. NextGen Component, Inc (*NextGen*) reserves the right to make changes to this document and its products and specifications at any time without notice. Customers should obtain and confirm the latest product information and specifications before final design, purchase or use.
- 3. NextGen makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, not does NextGen assume any liability for application assistance or customer product design.
- 4. NextGen does not warrant or accept any liability with products which are purchased or used for any unintended or unauthorized application. No license is granted by implication or otherwise under any intellectual property rights of NextGen.
- 5. NextGen products are not authorized for use as critical components in life support devices or systems without express written approval by NextGen.
- 6. NextGen requires that customers first obtain an RMA (Returned Merchandise Authorization) number prior to returning any products. Returns must be made within 30 days of the date of invoice, be in the original packaging, unused and like-new condition. At the time of quoting or purchasing, a product may say that it is Non-Cancelable/ Non-Returnable (NCNR). These products are not returnable and not refundable.